

Laser cut 5/10 mm Copper plate as been received, bending in circular curve with a tube.

Copper tape. Test assembly with bending copper plate and wedges (ship simulation) = OK.

Thermal insulation : polystyrene extrude (I go buy it tomorrow, Wednesday).

Tool to move ASU unity with suction pads are in study.

Thermal gel, required pressure is around 1 kg by cm<sup>2</sup>.  
4/10 mm special making is possible.

Aluminium for model as been received : We try to machine as soon as possible if is possible.

Assembly area for EUDET:

Hall 2 too expensive (budget cut shot, divide by 4!)

I look for a assembly area : Probably a temporary solution in building 209  
(An already installed not dusty room : air filtration but not clean room).

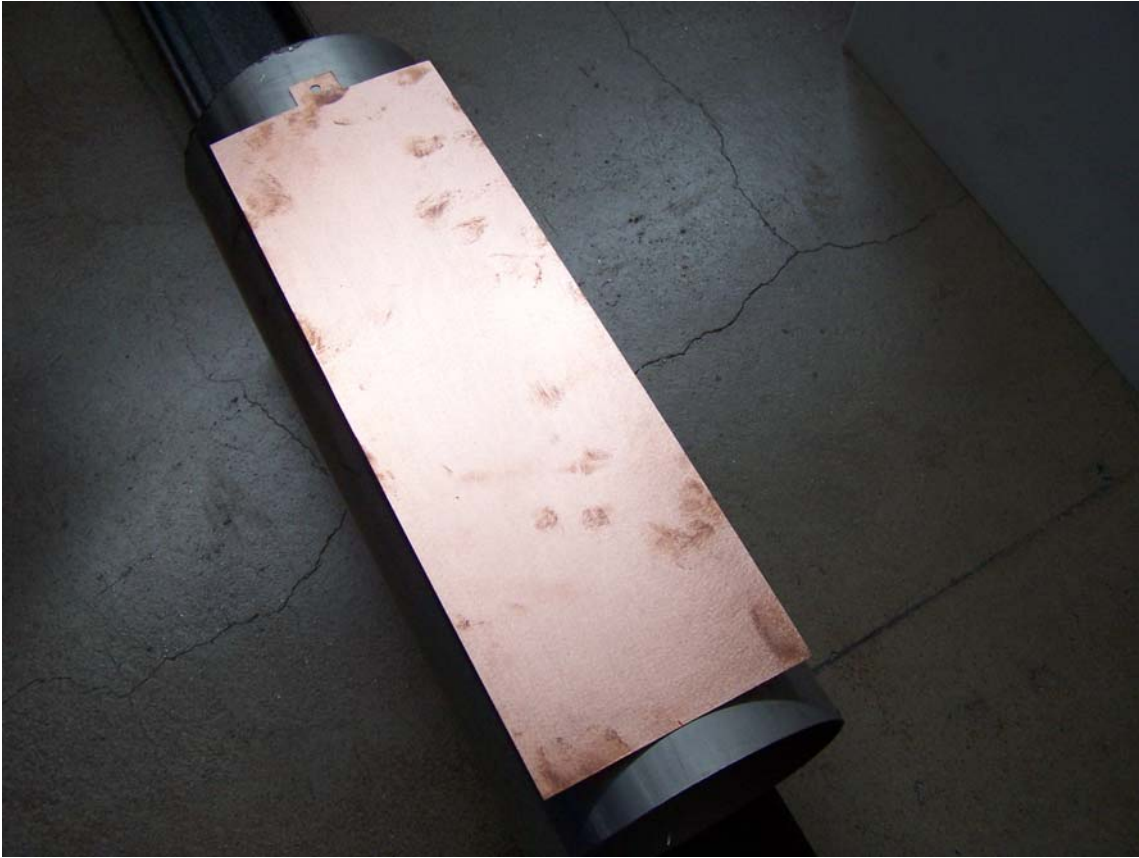
Try to modify the shape curve of bending copper (elipse). To a B better planarity of slab=> tests with short copper plate and after applied the method on long copper plate.

Or, bending long copper plate in circular curve for thermal test.

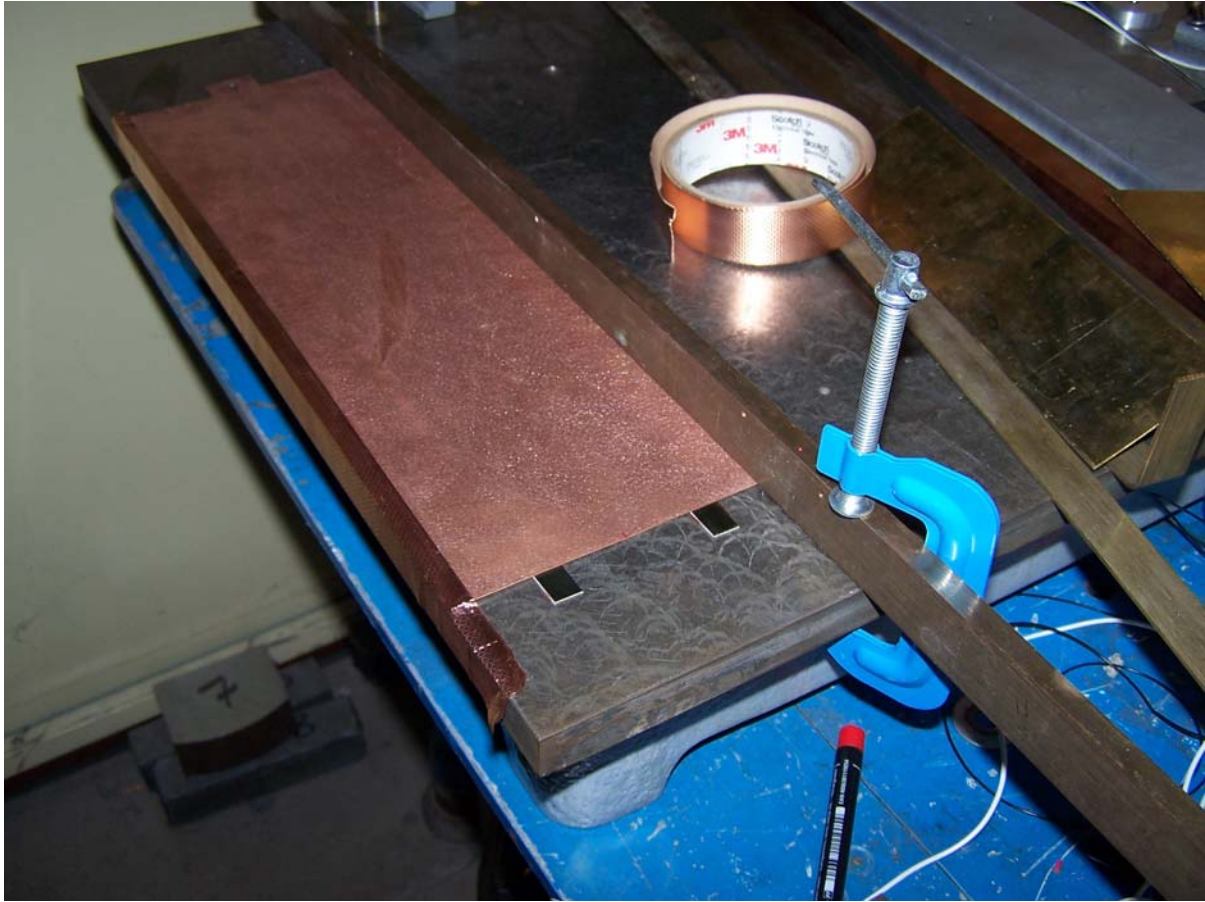
Modelling polystyrene insulation.



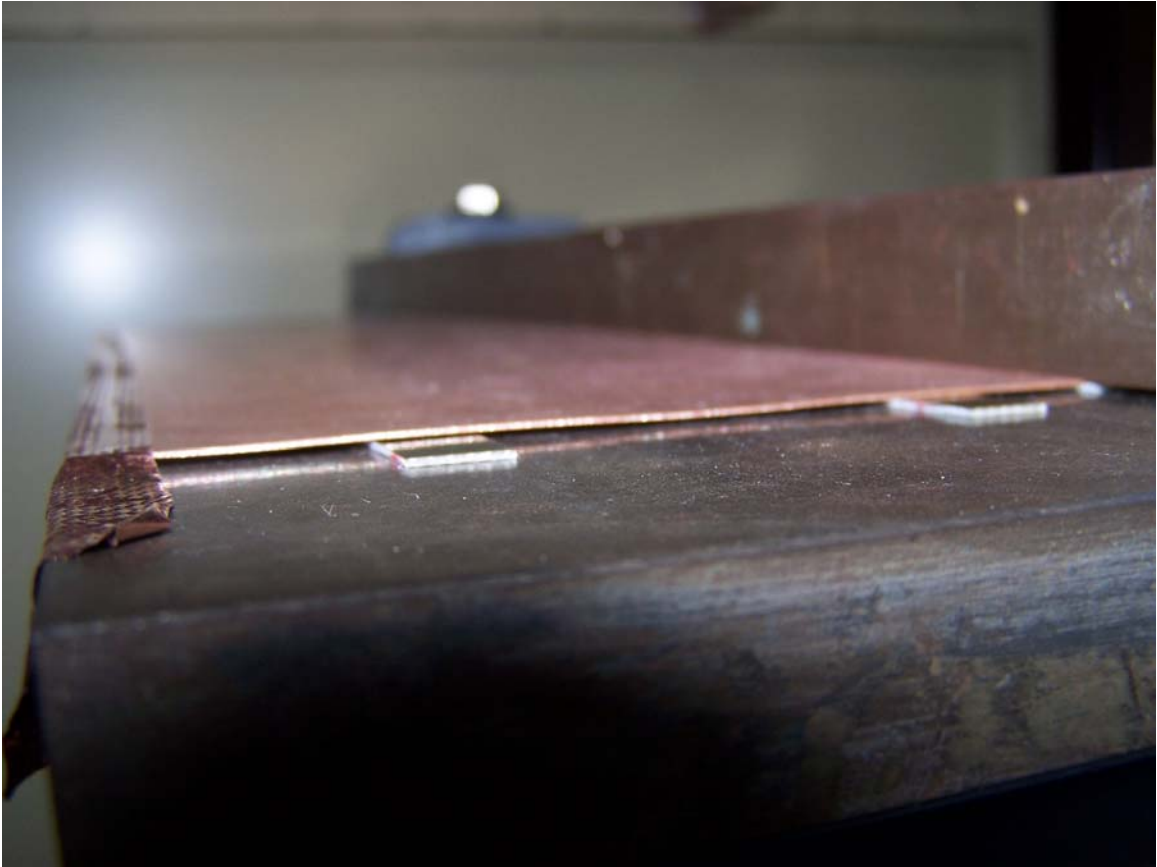
Laser cut copper plate received



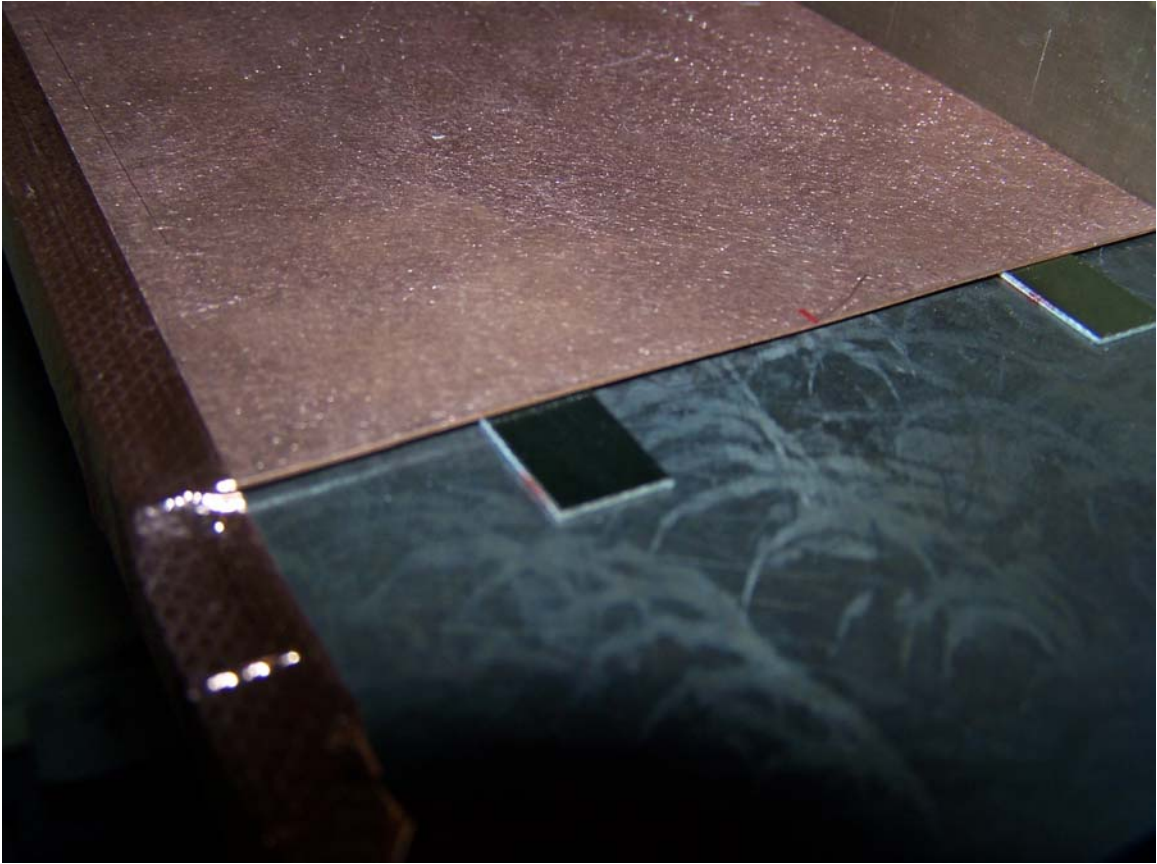
Circular bending of short copper plate on tube



Assembly test of copper plate with wedges



Zoom on assembly



Pressure on wedges is good: Difficult to move it.